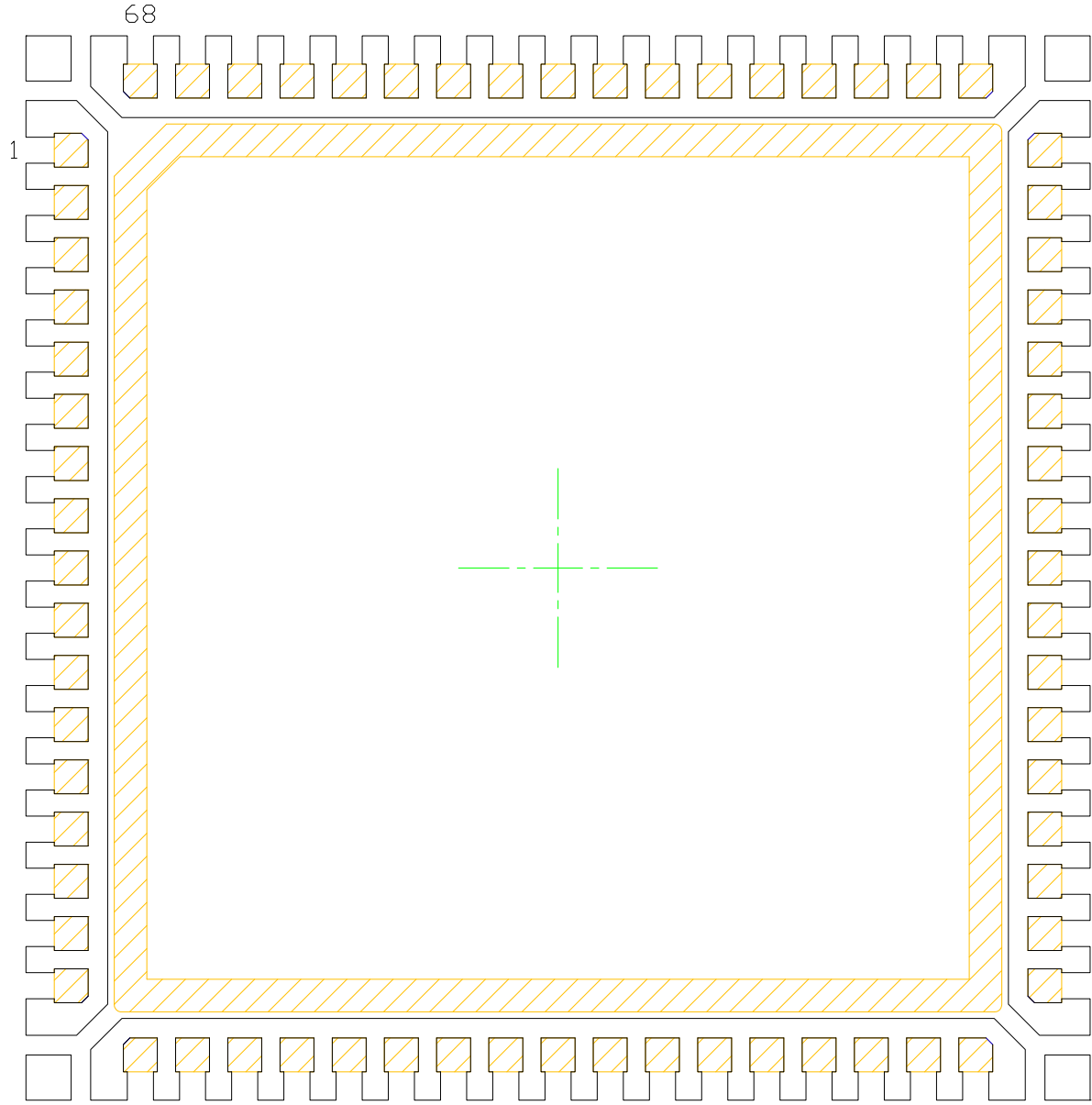



REVISIONS		
REV	DESCRIPTION	DATE
C	INCREASED DAP AND E-PAD SIZES	07/19/17



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	 www.promex-ind.com	
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 6.90 x 6.90 mm		
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 6.70 x 6.70 mm	TITLE	
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: SELECTIVE	QFN 68L 8X8 mm 0.40 PITCH BOND SHELL	
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	LEADFRAME P/N:	REV
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	235-00089	00
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	DO NOT SCALE	FILE NAME
			68L-QFN-8X8-40P-BD.DWG
			SHEET
			1 OF 1